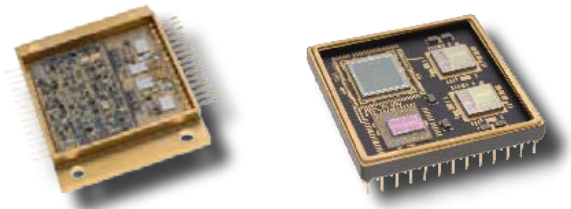


C-MAC is a world leader in the design and manufacture of high reliability electronic modules for harsh environments

'C-MAC's multi-chip modules can extend the life of electronic systems in harsh environments'

Extensive experience in our core markets supplying tier one companies in the aerospace and automotive industries has given us a great depth of knowledge of material systems for high temperature, high vibration environments. Our comprehensive testing at extreme temperatures provides an excellent grounding for pushing operating temperatures to 250°C (482°F).

Our specialist techniques of bare semiconductor die on thick film ceramic interconnect address the high temperature performance issues of traditional glass fibre based printed circuit boards (PCBs).



Benefits of C-MAC's Chip and Wire multi-chip modules

- » High temperature operation up to 225°C (437°F)
- » Monometalic wire bond and metal interconnect
- » Compatible with silicon on insulator (SoI) and silicon carbide (SiC) devices
- » Proven reliability
- » Increased packaging density
- » Choice of substrate carrier such as Alumina, LTCC, HTCC and others
- » Full range of hermetic packaging options available

Our products are featured in a wide range of extreme environment applications including:

The Energy and Industrial Sectors:

- » Solid state anemometer electronics
- » Offshore safety control systems
- » Pressure control sensors
- » Motor controllers

The Space Sector:

Multi-chip modules for

- » Artemis Satellite
- » International Space Station,
- » INMARSAT 1, 2, 3, 4



The Aerospace Sector:

- » Aircraft altimeter controls
- » MIL-STD-1553 databus products

The Automotive Sector:

- » Exhaust Gas Recirculation modules
- » Turbocharger controllers
- » High intensity discharge headlamp controls
- » Mass air flow and pressure sensors

The Medical Sector:

- » Surgical drill hermetic motor controllers
- » Blood electrolyte sensors
- » Blood analyser control hybrids

For further information contact:

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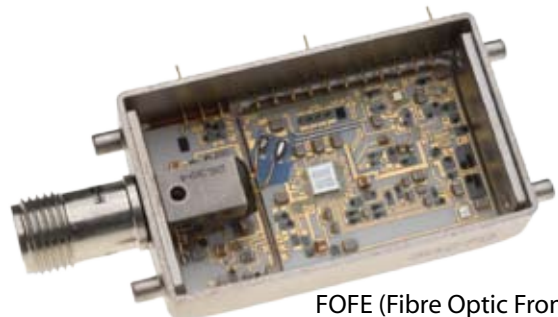
Tel: +44 (0) 1493 743 143

Email: michaelwoolsey@cmac.com

www.cmac.com

Our technologies and capabilities:

- » Thick film multilayer interconnect
- » Low Temperature Co-fired Ceramic (LTCC)
- » Gold and Aluminium wirebonding
- » Chip and wire assembly
- » Surface mount assembly
- » System assembly/box build
- » Printed Circuit Board (PCB) assembly
- » Electrical test
- » Environmental testing (qualification)



FOFE (Fibre Optic Front End),
installed in every Eurofighter jet

C-MAC
MicroTechnology

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